

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1. (Original) A semiconductor device comprising:
an IC chip for wirelessly transmitting/receiving data;
electrodes formed on a front surface and a rear surface of said IC chip; and
a first conductor and a second conductor connected respectively to said
electrodes,

wherein said first conductor and said second conductor are connected outside
said IC chip to form an antenna.

2. (Currently Amended) A semiconductor device comprising:
an IC chip for wirelessly transmitting/receiving data;
~~electrodes~~ a first electrode formed on a front surface of said IC chip and a
second electrode formed on ~~and~~ a rear surface of said IC chip; and
a first conductor and a second conductor connected respectively to said first
and second electrodes,
wherein said second electrode, formed on the rear surface of said IC chip,
has the same potential as that of the ~~a~~ a substrate of said IC chip.

3. (Currently Amended) A semiconductor device according to claim 1, further comprising:

~~—— an IC chip for wirelessly transmitting/receiving data;~~
~~—— electrodes formed on a front surface and a rear surface of said IC chip; and~~
~~—— a first conductor and a second conductor connected respectively to said electrodes,~~
~~—— wherein a slit is provided between said first conductor and said second conductor when viewed from a front surface side of said IC chip. chip, and said first conductor and said second conductor are connected to each other.~~

4. (Currently Amended) A semiconductor device according to claim 1, further comprising:

~~an IC chip for wirelessly transmitting/receiving data;~~
~~—— electrodes formed on a front surface and a rear surface of said IC chip; and~~
~~—— a first conductor and a second conductor connected respectively to said electrodes,~~
~~—— wherein a slit is provided in said first conductor or said second conductor. conductor, said first conductor and said second conductor are connected to each other.~~

5. (Original) A wireless identification semiconductor device comprising:
an IC chip for wirelessly transmitting/receiving data;
electrodes formed on a front surface and a rear surface of said IC chip; and
a conductor having a slit and including a first portion and a second portion

connected to said respective electrodes.

6. (Original) The wireless identification semiconductor device according to claim 5,

wherein said conductor is bent and connected to said electrodes.

7. (Currently Amended) The wireless identification semiconductor device according to claim 6,

wherein said conductor₁ before being bent and connected to said electrode₁ is accommodated in the form of a rectangular shape.

Claims 8-14 (Canceled without prejudice or disclaimer).

15. (New) A semiconductor device according to claim 4, wherein said conductor in which said slit is provided is bent.

16. (New) A semiconductor device according to claim 15,
wherein said conductor in which said slit is provided, before being bent and connected to said electrode, is accommodated in the form of a rectangular shape.

17. (New) A semiconductor device according to claim 2,
wherein a slit provided between said first conductor and said second conductor when viewed from a front surface side of said IC chip.

18. (New) A semiconductor device according to claim 2,
wherein a slit provided in said first conductor or said second conductor.

19. (New) A semiconductor device according to claim 17,
wherein at least one of said first or second conductors is bent.

20. (New) A semiconductor device according to claim 19,
wherein said conductor which is bent, before being bent and connected to
said electrode, is accommodated in the form of a rectangular shape.

21. (New) A semiconductor device according to claim 18,
wherein at least one of said first or second conductors is bent.

22. (New) A semiconductor device according to claim 21,
wherein said conductor which is bent, before being bent and connected to
said electrode, is accommodated in the form of a rectangular shape.